SN74LVCHR16245A 16-BIT BUS TRANSCEIVER WITH 3-STATE OUTPUTS

SCAS582G - NOVEMBER 1996 - REVISED JUNE 1999

 Member of the Texas Instruments Widebus™ Family 	DGG OR DL PACKAGE (TOP VIEW)			
 EPIC™ (Enhanced-Performance Implanted CMOS) Submicron Process 	1DIR 1 1B1 2	48 10E 47 1A1		
 Typical V_{OLP} (Output Ground Bounce) < 0.8 V at V_{CC} = 3.3 V, T_A = 25°C 	1B1 U2 1B2 U3 GND U4	46 1 1A2 45 GND		
 Typical V_{OHV} (Output V_{OH} Undershoot) 2 V at V_{CC} = 3.3 V, T_A = 25°C 	1B3 5 1B4 6	44 1 1A3 43 1A4		
 Supports Mixed-Mode Signal Operation on All Ports (5-V Input/Output Voltage With 3.3-V V_{CC}) 	V _{CC} [] 7 1B5 [] 8	42 V _{CC} 41 1A5		
Power Off Disables Inputs/Outputs, Permitting Live Insertion	1B6	40 1 1A6 39 GND 38 1 1A7		
 ESD Protection Exceeds 2000 V Per MIL-STD-883, Method 3015; Exceeds 200 V Using Machine Model (C = 200 pF, R = 0) 	1B8	36 2A1 35 2A2		
 Latch-Up Performance Exceeds 250 mA Per JESD 17 	GND 15 2B3 16 2B4 17	33 2A3		
 Bus Hold on Data Inputs Eliminates the Need for External Pullup/Pulldown Resistors 	V _{CC} 18 2B5 19	31 V _{CC} 30 2A5		
 All Outputs Have Equivalent 26-Ω Series Resistors, So No External Resistors Are Required 	2B6	27 2A7		
Package Options Include Plastic 300-mil	2DIR [24	25 2OE		

NOTE: For order entry:

The DGG package is abbreviated to G.

Small-Outline (DGG) Packages

For tape and reel:

The DGGR package is abbreviated to GR, and the DLR package is abbreviated to LR.

Shrink Small-Outline (DL) and Thin Shrink

description

This 16-bit (dual-octal) noninverting bus transceiver is designed for 1.65-V to 3.6-V V_{CC} operation.

The SN74LVCHR16245A is designed for asynchronous communication between data buses. The control-function implementation minimizes external-timing requirements.

This device can be used as two 8-bit transceivers or one 16-bit transceiver. It allows data transmission from the A bus to the B bus or from the B bus to the A bus, depending on the logic level at the direction-control (DIR) input. The output-enable (\overline{OE}) input can disable the device so that the buses are effectively isolated.

All outputs, which are designed to sink up to 12 mA, include equivalent $26-\Omega$ series resistors to reduce overshoot and undershoot.

To ensure the high-impedance state during power up or power down, \overline{OE} should be tied to V_{CC} through a pullup resistor; the minimum value of the resistor is determined by the current-sinking capability of the driver.

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description (continued)

Inputs can be driven from either 3.3-V or 5-V devices. This feature allows the use of these devices as translators in a mixed 3.3-V/5-V system environment.

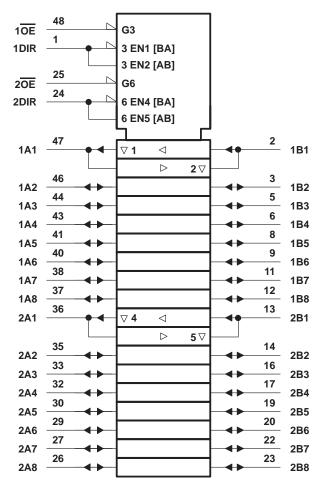
Active bus-hold circuitry is provided to hold unused or floating data inputs at a valid logic level.

The SN74LVCHR16245A is characterized for operation from -40°C to 85°C.

FUNCTION TABLE (each 8-bit section)

INP	UTS	ODEDATION				
OE	DIR	OPERATION				
L	L	B data to A bus				
L	Н	A data to B bus				
Н	X	Isolation				

logic symbol†

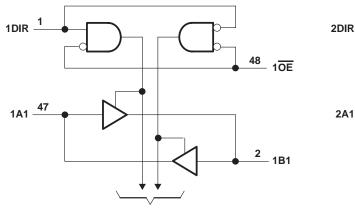


[†] This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

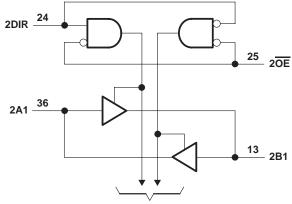


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logic diagram (positive logic)



To Seven Other Channels



To Seven Other Channels

absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

Supply voltage range, V _{CC} –0.5 V to 6.5 V Input voltage range, V _I (see Note 1)	
Voltage range applied to any output in the high-impedance or power-off state, VO	
(see Note 1)	(see Note 1)
Voltage range applied to any output in the high or low state, VO	Voltage range applied to ar
(see Notes 1 and 2)—0.5 V to V _{CC} + 0.5 V	(see Notes 1 and 2)
Input clamp current, I _{IK} (V _I < 0)	Input clamp current, IIK (VI
Output clamp current, I _{OK} (V _O < 0)	Output clamp current, IOK
Continuous output current, IO ±50 mA	Continuous output current,
Continuous current through each V _{CC} or GND±100 mA	Continuous current through
Package thermal impedance, θ _{JA} (see Note 3): DGG package	Package thermal impedance
DL package 97°C/W	
Storage temperature range, T _{stg} –65°C to 150°C	Storage temperature range

[†] Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

NOTES: 1. The input negative-voltage and output voltage ratings may be exceeded if the input and output current ratings are observed.

- 2. The value of V_{CC} is provided in the recommended operating conditions table.
- 3. The package thermal impedance is calculated in accordance with JESD 51.

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recommended operating conditions (see Note 4)

			MIN	MAX	UNIT	
\/	Cumbuyaltaga	Operating	1.65	3.6	V	
VCC Sup	Supply voltage Data r	Data retention only	1.5		V	
VIH High-level input voltage	V _{IH} High-level input voltage V _{CC} = 2.3 V	V _{CC} = 1.65 V to 1.95 V	0.65 × V _{CC}			
		V _{CC} = 2.3 V to 2.7 V	1.7		V	
		V _{CC} = 2.7 V to 3.6 V	2			
		V _{CC} = 1.65 V to 1.95 V		0.35 × V _{CC}		
V_{IL}	Low-level input voltage	V _{CC} = 2.3 V to 2.7 V		0.7	V	
	I —	V _{CC} = 2.7 V to 3.6 V		0.8		
٧ _I	Input voltage	•	0	5.5	V	
.,	Output voltage	High or low state	0	VCC	V	
VO		3-state	0	5.5	V	
	Liber Javes and a comment	V _{CC} = 1.65 V		-2		
la		V _{CC} = 2.3 V				
IOH	High-level output current	V _{CC} = 2.7 V		-8	mA	
		V _{CC} = 3 V		-12		
	Low-level output current	V _{CC} = 1.65 V		2		
		V _{CC} = 2.3 V		4	A	
IOL		V _{CC} = 2.7 V		8	mA	
		V _{CC} = 3 V		12		
Δt/Δν	Input transition rise or fall rate	•		10	ns/V	
TA	Operating free-air temperature		-40	85	°C	

NOTE 4: All unused control inputs of the device must be held at V_{CC} or GND to ensure proper device operation. Refer to the TI application report, Implications of Slow or Floating CMOS Inputs, literature number SCBA004.



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electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PAF	RAMETER			VCC	MIN	TYP [†]	MAX	UNIT	
		I _{OH} = -100 μA		1.65 V to 3.6 V	V _{CC} -0.	2			
		I _{OH} = -2 mA	1.65 V	1.2					
		I _{OH} = -4 mA		2.3 V	1.7				
VOH		IOH = -4 IIIA	2.7 V	2.2			V		
		I _{OH} = -6 mA	3 V	2.4					
		I _{OH} = -8 mA		2.7 V	2				
		I _{OH} = -12 mA		3 V	2				
		I _{OL} = 100 μA		1.65 V to 3.6 V			0.2		
		$I_{OL} = 2 \text{ mA}$		1.65 V			0.45		
		I _{OL} = 4 mA		2.3 V			0.7		
VOL		IOL - 4 IIIA		2.7 V			0.4	V	
		$I_{OL} = 6 \text{ mA}$		3 V			0.55		
		I _{OL} = 8 mA	2.7 V		0.6				
		I _{OL} = 12 mA	3 V			0.8			
ΙĮ	Control inputs	$V_{I} = 0 \text{ to } 5.5 \text{ V}$		3.6 V			±5	μΑ	
		V _I = 0.58 V	1.65 V	‡					
		V _I = 1.07 V	1.00 V	‡					
		V _I = 0.7 V	2.3 V	45			μΑ		
l(hold)	A or B ports	V _I = 1.7 V	2.0 1	-45					
		V _I = 0.8 V		3 V	75				
	V _I = 2 V		Ů ,	- 75					
		V _I = 0 to 3.6 V§		36 V			±500		
l _{off}		V _I or V _O = 5.5 V		0			±10	μΑ	
loz¶	V _O = 0 to 5.5 V		3.6 V			±10	μΑ		
Icc		$V_I = V_{CC}$ or GND,	IO = 0	3.6 V			20	μА	
		$3.6 \text{ V} \le \text{V}_{\text{I}} \le 5.5 \text{ V}^{\text{\#}}$	10 - 0	3.0 V			20	μΛ	
∆lcc		One input at V _{CC} – 0.6 V, Other inputs at V _{CC} or GND		2.7 V to 3.6 V			500	μΑ	
Ci	Control inputs	$V_I = V_{CC}$ or GND		3.3 V		3		pF	
C _{io}	A or B ports	$V_O = V_{CC}$ or GND	$V_O = V_{CC}$ or GND			12		pF	

switching characteristics over recommended operating free-air temperature range (unless otherwise noted) (see Figures 1 through 3)

PARAMETER	FROM (INPUT)	TO (OUTPUT)	V _{CC} =		V _{CC} =		VCC =	2.7 V	V _{CC} =		UNIT
	(INFOT)	(0011-01)	MIN	MAX	MIN	MAX	MIN	MAX	MIN	MAX	
t _{pd}	A or B	B or A	‡	‡	‡	‡		5.7	1.5	4.8	ns
t _{en}	ŌE	A or B	‡	‡	‡	‡		7.9	1.5	6.3	ns
t _{dis}	ŌĒ	A or B	‡	‡	‡	‡		8.3	2.2	7.4	ns

[‡] This information was not available at the time of publication.



[†] All typical values are at V_{CC} = 3.3 V, T_A = 25°C. ‡ This information was not available at the time of publication.

[§] This is the bus-hold maximum dynamic current. It is the minimum overdrive current required to switch the input from one state to another.

 $[\]P$ For I/O ports, the parameter IOZ includes the input leakage current, but not I_{I(hold)}. # This applies in the disabled state only.

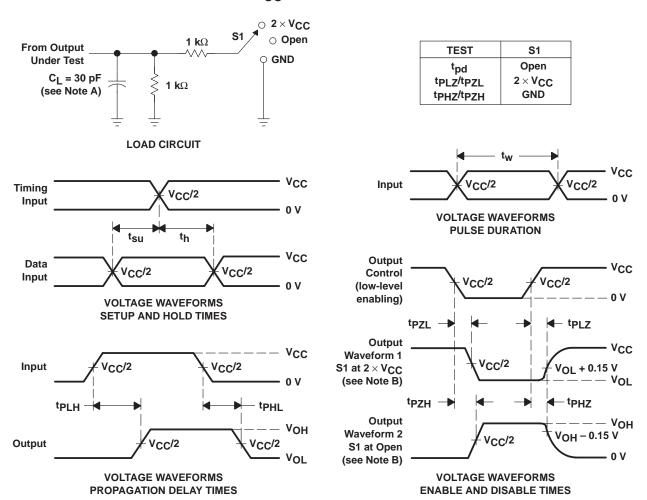
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operating characteristics, $T_A = 25^{\circ}C$

PARAMETER		TEST CONDITIONS	V _{CC} = 1.8 V TYP	V _{CC} = 2.5 V TYP	V _{CC} = 3.3 V TYP	UNIT	
Power dissipation capacitance		Outputs enabled	f 40 MH-	†	†	39	
opd per transceiver	Outputs disabled	f = 10 MHz	†	†	4	pF	

[†] This information was not available at the time of publication.

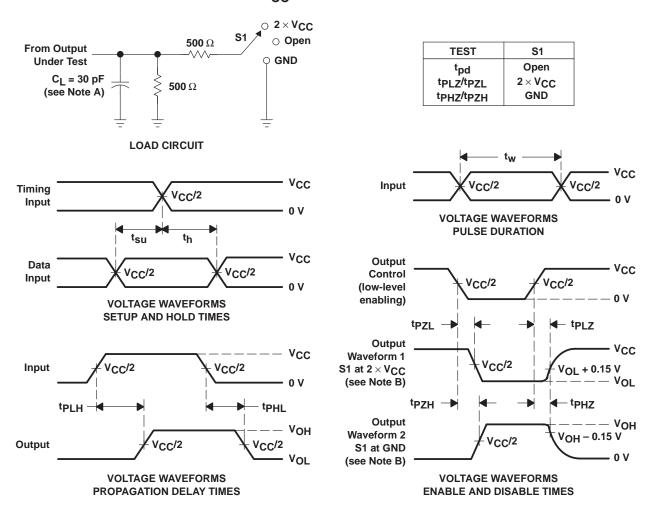
PARAMETER MEASUREMENT INFORMATION $V_{CC} = 1.8 \text{ V} \pm 0.15 \text{ V}$



- NOTES: A. C_L includes probe and jig capacitance.
 - B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
 - C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, Z_{O} = 50 $\Omega,\,t_{f}$ \leq 2 ns, t_{f} \leq 2 ns.
 - D. The outputs are measured one at a time with one transition per measurement.
 - E. tpLZ and tpHZ are the same as tdis.
 - F. tpzL and tpzH are the same as ten.
 - G. tpLH and tpHL are the same as tpd.

Figure 1. Load Circuit and Voltage Waveforms

PARAMETER MEASUREMENT INFORMATION V_{CC} = 2.5 V \pm 0.2 V



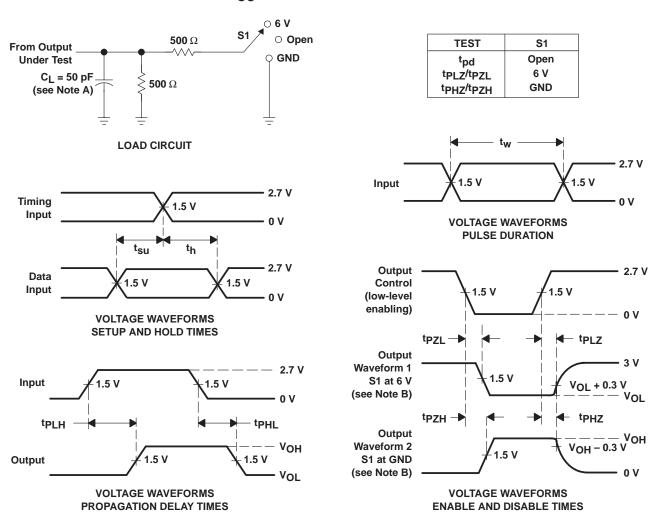
NOTES: A. C_L includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 10 MHz, Z_{O} = 50 $\Omega,\,t_{f}$ \leq 2 ns, t_{f} \leq 2 ns.
- D. The outputs are measured one at a time with one transition per measurement.
- E. tpLZ and tpHZ are the same as tdis.
- F. tpzL and tpzH are the same as ten.
- G. tpLH and tpHL are the same as tpd.

Figure 2. Load Circuit and Voltage Waveforms



PARAMETER MEASUREMENT INFORMATION V_{CC} = 2.7 V AND 3.3 V \pm 0.3 V



NOTES: A. C_I includes probe and jig capacitance.

- B. Waveform 1 is for an output with internal conditions such that the output is low except when disabled by the output control. Waveform 2 is for an output with internal conditions such that the output is high except when disabled by the output control.
- C. All input pulses are supplied by generators having the following characteristics: PRR \leq 0 MHz, $Z_O = 50 \Omega$, $t_f \leq$ 2.5 ns, $t_f \leq$ 2.5 ns.
- D. The outputs are measured one at a time with one transition per measurement.
- E. tpLz and tpHz are the same as tdis.
- F. tpzL and tpzH are the same as ten.
- G. tpLH and tpHL are the same as tpd.

Figure 3. Load Circuit and Voltage Waveforms



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